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## ON Semiconductor®

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**April 2015** 

## FDB082N15A

# N-Channel PowerTrench<sup>®</sup> MOSFET 150 V, 117 A, 8.2 m $\Omega$

#### **Features**

- $R_{DS(on)}$  = 6.7 m $\Omega$  (Typ.) @  $V_{GS}$  = 10 V,  $I_D$  = 75 A
- · Fast Switching Speed
- Low Gate Charge, Q<sub>G</sub> = 64.5 nC (Typ.)
- High Performance Trench Technology for Extremely Low  $R_{DS(on)}$
- · High Power and Current Handling Capability
- RoHS Compliant

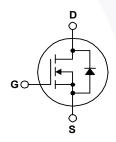
#### Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advance PowerTrench® process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

#### **Applications**

- · Synchronous Rectification for ATX / Server / Telecom PSU
- · Battery Protection Circuit
- · Motor drives and Uninterruptible Power Supplies
- · Micro Solar Inverter





#### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol		Parameter	FDB082N15A	Unit
V <sub>DSS</sub>	Drain to Source Voltage	150	V	
$V_{GSS}$	Gate to Source Voltage	- DC	±20	V
	Gate to Source voltage	- AC (f > 1 Hz)	±30	V
I <sub>D</sub>	- Continuous (T <sub>C</sub> = 25°C, Silicon Limited)		117	^
	Drain Current	- Continuous (T <sub>C</sub> = 100°C, Silicon Limited)	83	Α
I <sub>DM</sub>	Drain Current	- Pulsed (Note 1)	468	Α
E <sub>AS</sub>	Single Pulsed Avalanche Energ	y (Note 2)	542	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	6	V/ns
D	Dower Dissipation	$(T_C = 25^{\circ}C)$	294	W
$P_{D}$	Power Dissipation - Derate Sbove 25°C		1.96	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Tempera	ature Range	-55 to +175	°C
Tı	Maximum Lead Temperature fo	r Soldering, 1/8" from Case for 5 Seconds	300	οС

#### **Thermal Characteristics**

Symbol	Parameter FDB082N15A			
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.51	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	°C/VV	

## **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FDB082N15A	FDB082N15A	D <sup>2</sup> -PAK	Tape and Reel	330 mm	24 mm	800 units

## **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V, T_C = 25^{\circ}C$	150	-	-	V
ΔBV <sub>DSS</sub> / ΔΤ <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, Referenced to 25°C	-	0.08	-	V/°C
1	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V	-	-	1	μА
IDSS	Zero Gate voltage Drain Current	$V_{DS} = 120 \text{ V}, T_{C} = 150^{\circ}\text{C}$	-	-	500	μΑ
$I_{GSS}$	Gate to Body Leakage Current	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V	-	-	±100	nA

#### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2.0	-	4.0	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 75 A	1	6.7	8.20	mΩ
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 75 A	1	139	-	S

#### **Dynamic Characteristics**

_							
C <sub>iss</sub>	Input Capacitance	V - 25 V V - 2 V		\	4645	6040	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz		-	1445	1880	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 101112		-	100	-	pF
C <sub>iss</sub>	Input Capacitance	V - 75 V V - 0 V		-	4570	6040	pF
Coss	Output Capacitance	$V_{DS} = 75 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1  MHz		-	460	1880	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 101112		-	20	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10V			-	64.5	84	nC
$Q_{gs}$	Gate to Source Gate Charge	$V_{DS} = 120 \text{ V}, I_{D} = 75 \text{ A},$		-	19.1	-	nC
Q <sub>gs2</sub>	Gate Charge Threshold to Plateau	V <sub>GS</sub> = 10 V		-	8.7	-	nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		(Note4)	-	13.5	-	nC
ESR	Equivalent Series Resistance (G-S)	f = 1 MHz		-	2.5	-	Ω

#### **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 75 V, I <sub>D</sub> = 75 A,	-	22	54	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, R_{G} = 4.7 \Omega$	/ -	58	126	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	61	132	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note4)	-	26	62	ns

#### **Drain-Source Diode Characteristics**

I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current			-	117	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current			-	468	Α
$V_{SD}$	Drain to Source Diode Forward Voltage V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 75 A		-		1.25	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 75 A,	-	96	// -	ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	268	\\ - \\	nC

#### Notes

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. Starting  $T_J$  = 25°C, L = 3 mH,  $I_{SD}$  = 19 A.
- 3. I  $_{SD} \leq 75$  A, di/dt  $\leq 200$  A/µs, V  $_{DD} \leq BV_{DSS},$  starting T  $_{J}$  = 25°C.
- 4. Essentially independent of operating temperature typical characteristics.

## **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

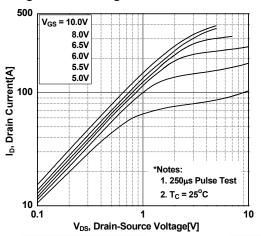


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

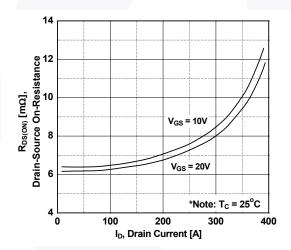


Figure 5. Capacitance Characteristics

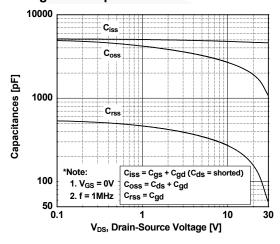


Figure 2. Transfer Characteristics

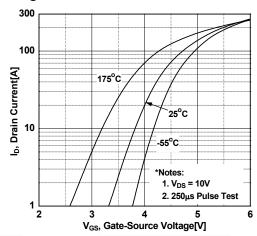


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

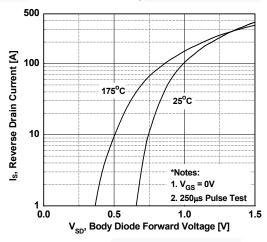
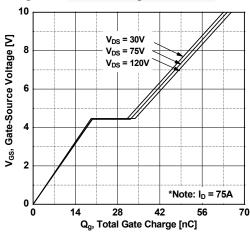


Figure 6. Gate Charge Characteristics



## **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

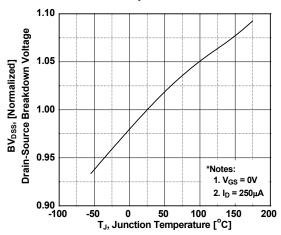


Figure 9. Maximum Safe Operating Area

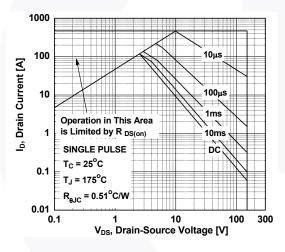


Figure 11. Unclamped Inductive Switching Capability

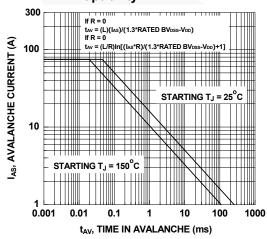


Figure 8. On-Resistance Variation vs. Temperature

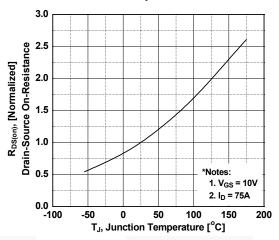
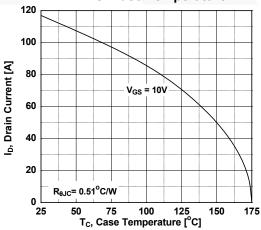
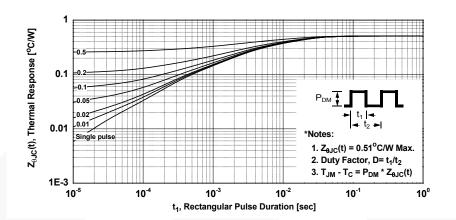


Figure 10. Maximum Drain Current vs. Case Temperature



## **Typical Performance Characteristics**

**Figure 12. Transient Thermal Response Curve** 



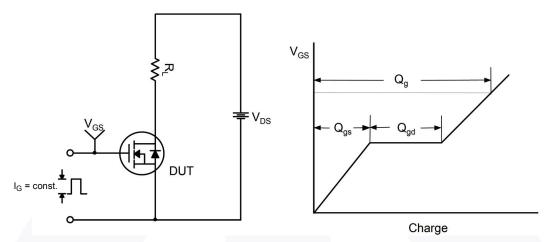


Figure 13. Gate Charge Test Circuit & Waveform

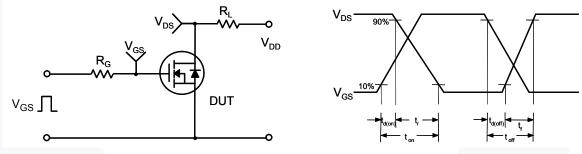


Figure 14. Resistive Switching Test Circuit & Waveforms

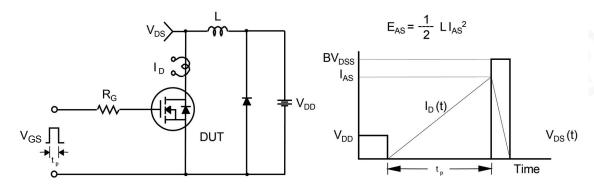


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

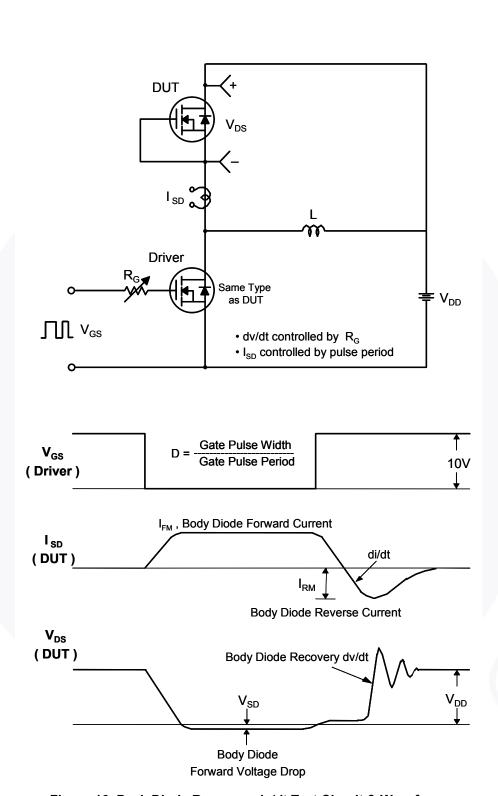
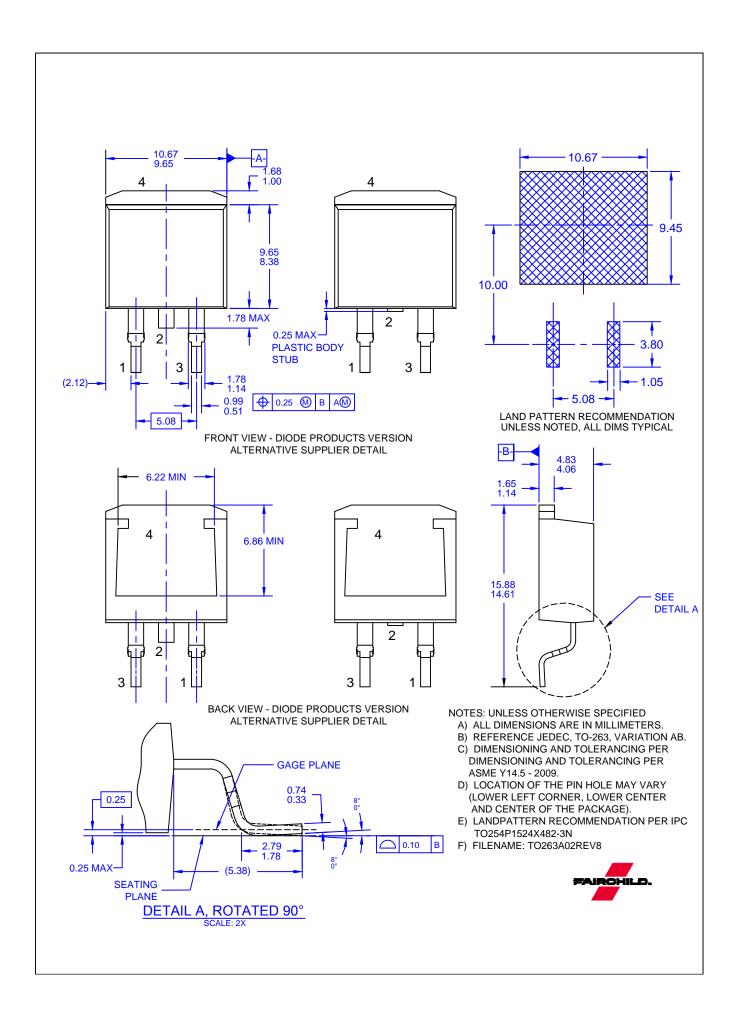


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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